



25th International Conference on Electronic Packaging Technology

August 07 to 09, 2024, Tianjin, China

<http://www.icept.org>

Speech subject: **Advanced Packaging Processes and Co-Design Simulation Solutions for 2.5D**

Integration

Speech leader: Jiaqi Fan, Advanced Packaging Design Manager, National Center for Advanced Packaging Co., Ltd.(NCAP China)

Speech Description/Objective:

As Moore's Law slows down, packaging technology has become a crucial means for the miniaturization, multifunctionality, reduced power consumption, and increased bandwidth of electronic products. Chip packaging is evolving from traditional planar packaging to system integration, high-speed, high-frequency, and three-dimensional directions. There are still many challenges in chip-package co-design and in using cost-effective materials and processes to meet various reliability requirements.

Speech Outline:

1. Background and Development Status of 2.5D Technology
2. System Integration Requirements and Associated Challenges
3. Introduction to NCAP's Design and Simulation Technology Capabilities

Who Should Attend:

For those interested in advanced packaging design and simulation, high-performance computing, and system integration.

Introduction of Speaker:

With 6 years of experience in the field of advanced packaging design, primarily engaged in the design and simulation research of 2.5D/3D integrated packaging, wafer-level fan-out packaging, and 3D heterogeneous integration.